

Special Issue

Seismic-Resistant Materials, Devices and Structures

Message from the Guest Editors

Earthquake resilience is a critical concern in the design and construction of modern infrastructure. The development of innovative materials and structural systems that can withstand seismic forces is essential to ensure the safety and longevity of buildings and other structures. In this Special Issue, we invite submissions that delve into the latest research and advancements in earthquake structures and materials. We welcome both theoretical and experimental studies, as well as comprehensive reviews and survey papers. Topics of interest include, but are not limited to, innovative materials for seismic applications, advanced structural systems, seismic performance assessment, retrofitting techniques, and case studies of earthquake-resistant design and construction.

Guest Editors

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Deadline for manuscript submissions

closed (20 June 2025)



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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